

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6532036

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NOBUHIKO SASAKI	01/28/2021
TAKANORI SAWADA	02/01/2021
TOSHIYUKI SHIMAMORI	01/29/2021
CHIE YABUTANI	02/01/2021
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECH CORPORATION
Street Address:	17-1, TORANOMON 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-6409
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17265726
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-568-6400
Email:	jchilson@vklaw.com
Correspondent Name:	VOLPE KOENIG
Address Line 1:	30 SOUTH 17TH STREET, 18TH FLOOR
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI5-611800038US01
NAME OF SUBMITTER:	GERALD B. HALT, JR.
SIGNATURE:	/Gerald B. Halt, Jr./
DATE SIGNED:	02/03/2021
Total Attachments: 1	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECH CORPORATION, a corporation organized under the laws of Japan, located at 17-1, Toranomon 1-chome, Minato-ku, Tokyo 105-6409, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECH CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

AUTOMATIC ANALYSIS SYSTEM

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECH CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECH CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Nobuhiko Sasaki</u> (Nobuhiko SASAKI)	<u>1/28/2021</u>
2) <u>Takanori SAWADA</u> (Takanori SAWADA)	<u>2/1/2021</u>
3) <u>Toshiyuki Shimamori</u> (Toshiyuki SHIMAMORI)	<u>1/29/2021</u>
4) <u>Chie Yabutani</u> (CHIE YABUTANI)	<u>2/1/2021</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____